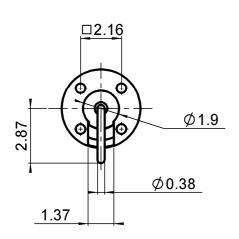
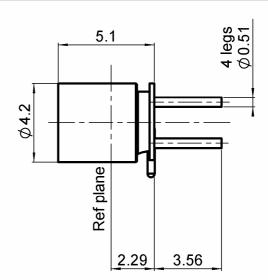
PIN IN PASTE - FULL DETENT

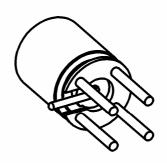
R222.428.000

Series: SMP









All dimensions are in mm.



	COMPONENTS	MATERIALS	PLATINGS (μm)
_	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	STAINLESS STEEL + BRASS BERYLLIUM COPPER - PTFE	PASSIVATED + GOLD 0.5 OVER NICKEL 2 GOLD 1.27 OVER NICKEL 1.27

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



PIN IN PASTE - FULL DETENT

R222.428.000

Series: SMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-18 GHz

Frequency **0-18** GHz VSWR **1.15*** + **0,0000** x F(0)

VSWR 1.15* + 0,0000 x F(GHz) Maxi Insertion loss 0.12 $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 5000 M Ω mini

ENVIRONMENTAL

Operating temperature -65/+165 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

Compliant with MIL-STD-348
*At 12,4 GHz - Performance strongly depends on lay out and pcb material

MECHANICAL CHARACTERISTICS

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3500** g

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be



PIN IN PASTE - FULL DETENT

R222.428.000

Series: SMP

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

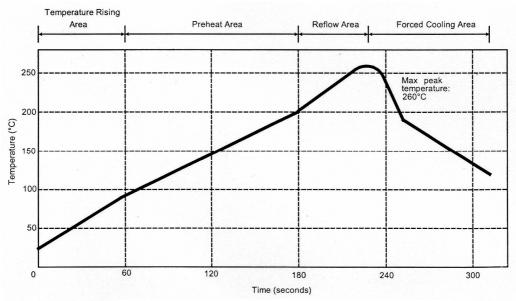
We advise a thickness of 150 microns (5.85 microinch). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary



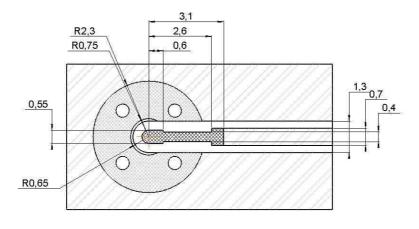
PIN IN PASTE - FULL DETENT

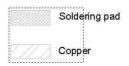
R222.428.000

Series: SMP

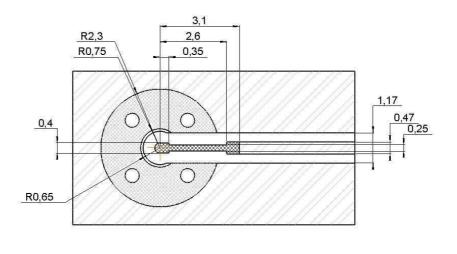
RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35μ m on both sides: Add vias between both sides along upper ground plane according to engineering practise





Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides : Add vias between both sides along upper ground plane according to engineering practise





Issue: 0914 C

In the effort to improve our products, we reserve the right to make changes judged to be necessary.

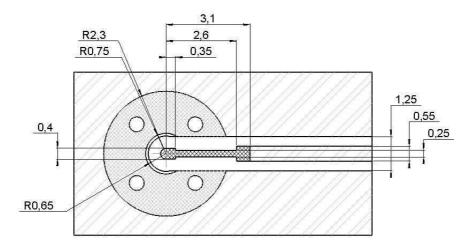


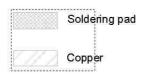
PIN IN PASTE - FULL DETENT

R222.428.000

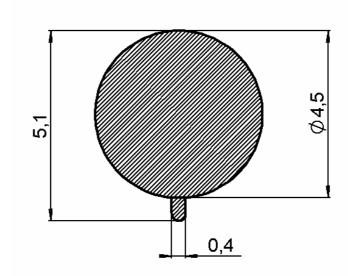
Series: SMP

Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise





SHADOW FOR VIDEO CAMERA



Issue: 0914 C In the effort to improve our products, we reserve the right to make changes judged to be necessary.

